Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]
HP TouchSmart 9100 Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>10</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>9</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>4</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers: 0

Components, parts and materials containing radioactive substances: 0

1.3 Markings for plastic parts greater than 25 grams

<table>
<thead>
<tr>
<th></th>
<th></th>
<th></th>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>M5 REAR FRAME A</td>
<td>rear frame</td>
<td>239.34</td>
<td>&gt;ABS&lt;</td>
<td></td>
</tr>
<tr>
<td>M5 REAR PANEL</td>
<td>rear panel</td>
<td>354.16</td>
<td>&gt;ABS&lt;</td>
<td></td>
</tr>
<tr>
<td>M5 FRONT BEZEL</td>
<td>bezel</td>
<td>161.75</td>
<td>&gt;ABS&lt;</td>
<td></td>
</tr>
<tr>
<td>M5 CHIN</td>
<td>chin</td>
<td>124.1</td>
<td>&gt;ABS&lt;</td>
<td></td>
</tr>
<tr>
<td>M5 REAR PANEL BTM</td>
<td>panel bottom</td>
<td>147.01</td>
<td>&gt;ABS&lt;</td>
<td></td>
</tr>
<tr>
<td>M5 REAR FRAME _ B</td>
<td>rear frame</td>
<td>254</td>
<td>&gt;ABS&lt;</td>
<td></td>
</tr>
<tr>
<td>M5 SIDE CAP LF</td>
<td>side cap left</td>
<td>26.17</td>
<td>&gt;ABS&lt;</td>
<td></td>
</tr>
<tr>
<td>M5 SIDE CAP LF W/O Asklight_Btn</td>
<td>side cap left bottom</td>
<td>25.19</td>
<td>&gt;ABS&lt;</td>
<td></td>
</tr>
<tr>
<td>M5 INNER BEZEL</td>
<td>inner bezel</td>
<td>78.02</td>
<td>&gt;ABS&lt;</td>
<td></td>
</tr>
<tr>
<td>M5 IO DOOR</td>
<td>Input/ouput connector door</td>
<td>44.59</td>
<td>&gt;ABS&lt;</td>
<td></td>
</tr>
<tr>
<td>STAND_TRIM</td>
<td>stand trim</td>
<td>52.15</td>
<td>&gt;PMMA&lt;</td>
<td></td>
</tr>
<tr>
<td>STAND_COVER</td>
<td>stand cover</td>
<td>58.33</td>
<td>&gt;ABS&lt;</td>
<td></td>
</tr>
<tr>
<td>Thermal Housing</td>
<td>fan housing</td>
<td>29.9g</td>
<td>&gt;PET&lt;</td>
<td></td>
</tr>
</tbody>
</table>

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td></td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
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<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. 
2. 
3. 
4. 
5. 
6. 
7. 
8. 

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
**Figure 1: Mechanical parts disassembly**

1) Place the system

2) Dongle holder and I/O cover

3) Trim and B-CAS, ODD cover
4) Foot and rear cover

Disassemble screw on foot (Right & left side) with electrical screw driver and place it in material box.

Loosse screw on low rear cover and pull it off from unit.
5) Stand

1. Disassembly IO-clip
2. Remove 4 screws on stand
3. Take the stand out of unit and put it on material area

6) Rear frame

PSG instructions for this template are available at EL-MF877-01
7) DDR shielding

- Remove IO Inset part
- Disassemble DDR shielding
8) Amp shielding

Dis-lock 2pcs screws on AMP SHIED
Take AMP shield out

9) Rear shielding

Disassemble 7pcs screws on rear shield
Take rear meter shield from chassis
Put rear meter shield on material area

10) Side cap

Disassembly right side cap
Plug AMB cable from connector
Dis-lock 2pcs screw on AMB board
11) ODD

1. Plug ODD SATA & Power cable from ODD
2. Dis-lock one pcs screw and take ODD from chassis

12) HDD

1. Dis-lock HDD screw and take HDD out from unit
2. 
3. Disassemble HDD from HDD cage
13) Some cables and Inverter board cage

- Plug HDD SATA+POWER, ODD SATA+POWER, ODD Eject from MB
- Disassembly inverter brk and pull the brk out hook

14) Thermal module

- Take dongle plastic moudle out
- Dis-lock 8pcs screws on MXM H/S
- Dis-lock 3pcs screw on system fan
15) MB and Amp board

- Disassemble 7pcs screws from CPU thermal kit as picture
- MXM card should lose 2pcs screw to be moved
- Disassemble WLAN card from MB
- Press the hook and pull the LVDS cable form LCD side
- Loose TV card screws and plug out TV card from MB
- Disassemble 5pcs screws on MB and take MB from chassis
- Detach speaker screws

PSG instructions for this template are available at EL-MF877-01
16) CR

Disassemble Card reader and take it out of card reader shield

17) Microphone

Dis-lcock Mic-phone card and take away

18) Webcam

Disassemble camera module kit
19) DSP board

20) Inverter board

Figure 2: Touch panel kit disassembly
1) Front bezel

1. Put NO TPK on rotating jig with top side down. Then use static bag to cover TFC cable in order to protect it.
2. Remove acrylic tape which is used for fixing TFC cable from left to right. Then route TFC cable outside of bezel. Notice: No damage MFC cable when removing tapes.
3. Remove 4 screws for fixing TOP bracket in turn as pic. Then take TOP bracket off.
4. Remove 4 screws for fixing front bezel and R/L bracket in turn. Disassemble bezel and TPK.
5. Put TPK on rotating jig after disassembling it. Notice: Camera kit needs to hang in the air without any pressure. Then remove screws for locking R/L bracket, take R/L bracket off.

2) Camera kit

1. Put TPK upward and disassemble 4 metal clips with feeler gauge pushed on the edge of metal. As the Pic. Notice: Don't check camera or session camera during the repair anymore.
2. Power on the bank. Set the temperature at 40°C.
3. When the tank temperature reached 40°C, put TPK in the tank for 10min and make the TPK upward. Close the tank door and record the time.
4. Put TPK on the EPDM foam and cut from camera kit bottom (camera 1) (just the left Pic). Move the feeler gauge slowly from the red line position (please don't separate the top camera kit position). Then separate camera kit from TPK. Notice: Please start with much strength when cutting and removing to avoid scratching camera kit and gate.
5. Remove the camera kit from TPK with as the Pic.
   Note: Before removal, make sure the TFC cable free, the strength should be the same during the process. Don't touch camera kit or MFC.
6. Remove camera 2 in the same way as camera 1.
   Note: Before removal, make sure the TFC cable free, the strength should be the same during the process. Don't touch camera kit or MFC.
3) Glass

1. Put the TSPK upwards on the table. Cut TSGP from the 30 degree. The cutting depth is 3-5mm.

2. Hold the TSGP and cut TSGP from the top to bottom. Pull the knife by 30 degree and the left side of TSGP will be separated.

3. Rotate the TPK 90 degree by contra clock wise. Pull knife from the right-top corner and cut the TSGP.

4. Hold the TSGP and cut the bottom side. Pull the knife by 30 degree. The 4 sides for TSGP will all be separated by this way.

5. After making sure all the 4 sides of TPK are all cut, separate TS glass & panel. Note: Don't pull with much strength or break glass when separating.

6. Compare the Camera Kit S/N with DSP S/N and make sure the S/N are the same. Note: FFC should be protected with ESD bag when putting in the material box as the Pic.
**Figure 3 : Remove molded-in NUT from Chin**

1) Use a metal pin, diameter is 2.5mm.

2) Metal pin aims at NUT.

3) Insert the metal pin into NUT around 3-4mm.
4) Press metal pin until NUT depart from plastic.

5) Remove NUT fully.